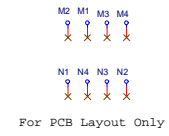
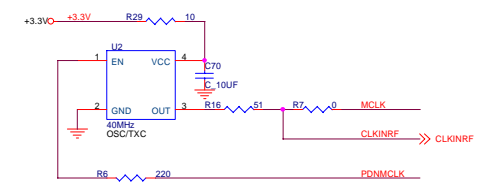


NOTE : REFERENCE USB2.0 PCB LAYOUT GUIDELINES

1. PCB : FR4 material (Er = 4.5)
2. PP : 7 mil
3. WIDTH : 12 mil
4. THICKNESS : 1/2 oz copper (0.7mil)
5. D+/-D- DISTANCE : 14 mil
6. GROUND SEPARATION >=12 mil
7. BOARD THICKNESS = 62 mil (1.57 mm)

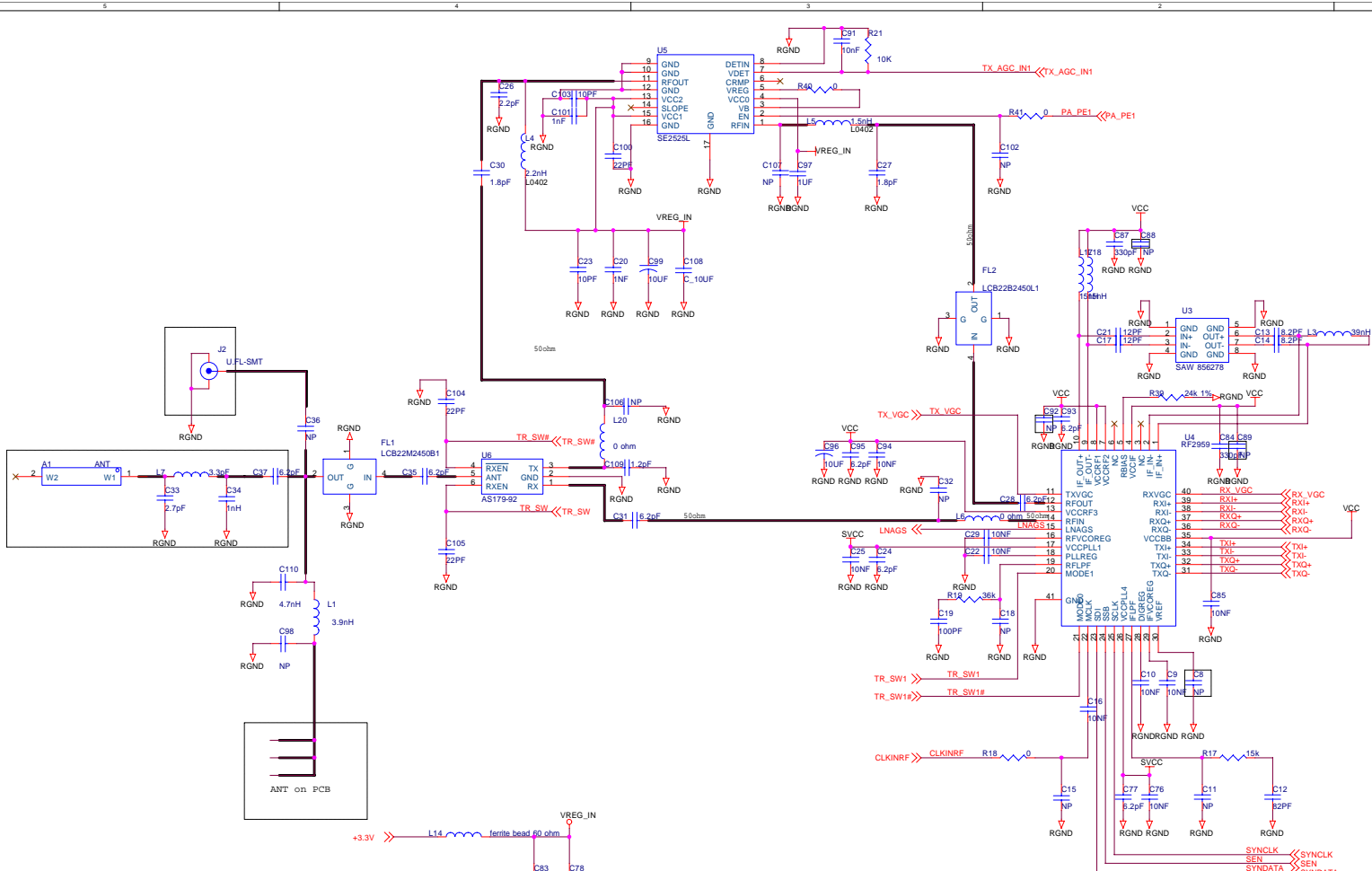
9/3 Ohm

OSCILLATOR CIRCUIT FOR MAC/ RF



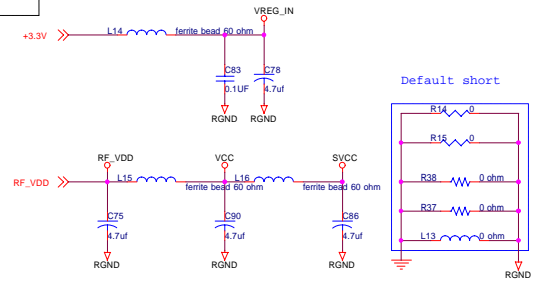
For PCB Layout Only

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- LAYER 1** — 1/2 OZ Cu
- LAYER 2** — FR4--7 mil
- LAYER 3** — 1 OZ Cu
- LAYER 4** — FR4--15 mil
- LAYER 5** — 1 OZ Cu
- LAYER 6** — FR4--8mil
- LAYER 7** — 1 OZ Cu
- LAYER 8** — FR4--15 mil
- LAYER 9** — 1 OZ Cu
- LAYER 10** — FR4-- 7 mil
- LAYER 11** — 1/2 OZ Cu

— 50 Ohm RF thickness line 12 mil width
 The RF lines minimum space widths are 15 mil



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